

MAGNETIC AMPLIFIER CONTROLLER

FEATURES

- Independent 1% Reference
- Two Uncommitted, Identical Operational Amplifiers
- 100-mA Reset Current Source With –120-V Capability
- 5-V to 40-V Analog Operation
- 5-W DIP Package

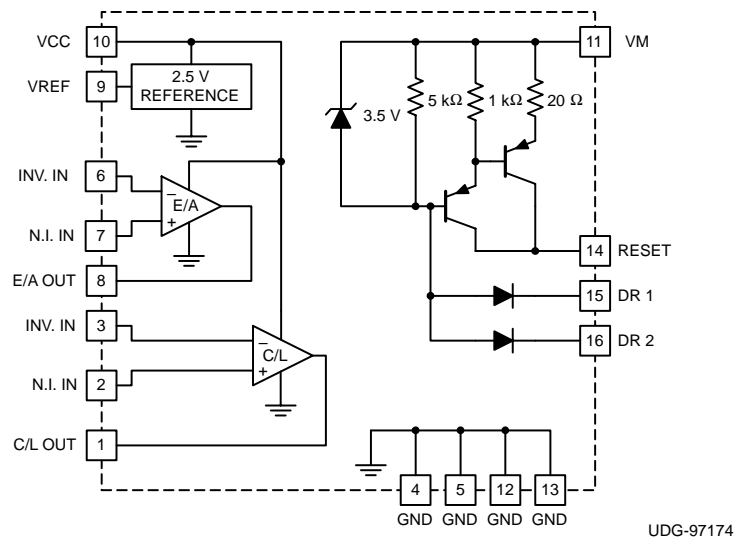
DESCRIPTION

The UC3838 and the UC3838A family of magnetic amplifier controllers contains the circuitry to generate and amplify a low-level analog error signal along with a high voltage-compliant current source. This source provides the reset current necessary to enable a magnetic amplifier to regulate and control a power supply output in the range of 2 A to 20 A.

The UC3838A originally was a parametric improvement version of the UC3838 which since has been used for both versions. There is no difference between the UC3838A and UC3838 version.

By controlling the reset current to a magnetic amplifier, this device defines the amount of volt-seconds the magnetic amplifier blocks before switching to the conducting state. Magnetic amplifiers are ideal for post-regulators for multiple-output power supplies where each output can be independently controlled with efficiencies up to 99%. With a square or pulse-width modulated input voltage, a magnetic amplifier blocks a portion of this input waveform, allowing just enough to pass to provide a regulated output. With the UC3838/A, only the magnetic amplifier coil, three diodes, and an output L-C filter are necessary to implement a complete closed-loop regulator.

BLOCK DIAGRAM



AVAILABLE OPTIONS

$T_A = T_J$	Packaged Devices		
	SOIC Wide (DW)	PDIP (N)	PLCC (Q)
–20°C to 85°C	UC2838DW	UC2838N	UC2838Q
	UC2838ADW	UC2838AN	UC2838AQ
0°C to 70°C	UC3838DW	UC3838N	UC3838Q
	UC3838ADW	UC3838AN	UC3838AQ

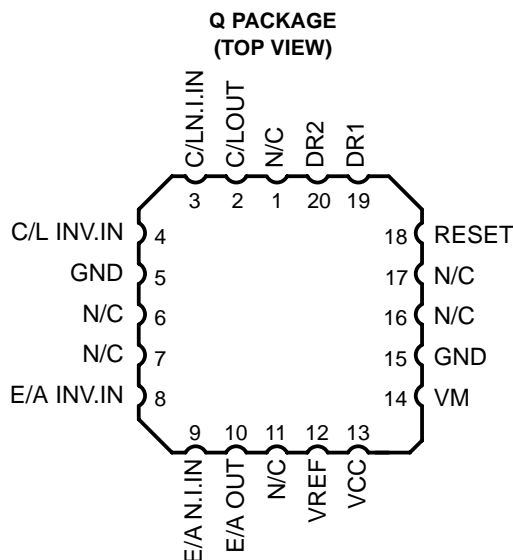
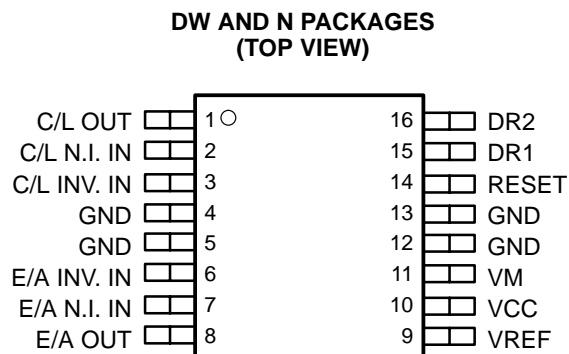
UC2838, UC2838A UC3838, UC3838A

SLUS221A – APRIL 2000 – REVISED MAY 2001

description (continued)

The UC3838/A contains a precision 2.5-V reference, two uncommitted high-gain operational amplifier and a high-gain PNP-equivalent current source which can deliver up to 100 mA of magnetic amplifier reset current and with -120-V capability.

These devices are available in a plastic batwing DIP (N), wide body SOIC (DW), and PLCC (Q) package for operation over a -20°C to 85°C temperature range.



absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, V_{CC}	40 V
Magnetic amplifier source voltage, VM	40 V
Reset output voltage, VR	-120 V
Total current source voltage, VM – VR	-140 V
Amplifier input range	-0.3 V to VCC
Reset input current, DR1 and DR2	-10 mA
Power dissipation at $T_A = 25^{\circ}\text{C}$	
Q, N, DW package	2 W
Power dissipation at T (leads/case) = 25°C	
Q, N, DW package	5 W
Operating temperature range, T_J	-55°C to 125°C
Storage temperature range, T_{stg}	-65°C to 150°C
Lead temperature (soldering, 10 sec)	300°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

‡ All voltages are with respect to ground pins. All currents are positive into the specified terminal. Consult packaging section of data book for thermal limitations and considerations of package.

electrical characteristics, $T_A = -20^{\circ}\text{C}$ to 85°C for the UC2838/A, and $T_A = 0^{\circ}\text{C}$ to 70°C for the UC3838/A, $V_{CC} = 20\text{ V}$, $V_M = 5\text{ V}$, $T_A = T_J$, (unless otherwise stated)

reference

PARAMETER	TEST CONDITIONS	UC2838/UC2838A			UC3838/UC3838A			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
Supply current	$V_{CC} = V_M = 40\text{ V}$		4	8		4	8	mA
Reference output	$T_A = 25^{\circ}\text{C}$	2.47	2.50	2.53	2.45	2.50	2.55	V
Line regulation	$V_{CC} = 5\text{ V}$ to 30 V		1	5		1	10	mV
Load regulation	$I_O = 0\text{ mA}$ to -2 mA		5	20		5	20	mV
Short-circuit current	$V_{REF} = 0\text{ V}$		-30	-60		-30	-60	mA
Temperature stability	See Note 1		15	25		10	25	mV

NOTE: 1. These parameters are ensured by design but not 100% tested in production.

amplifier (each amplifier)

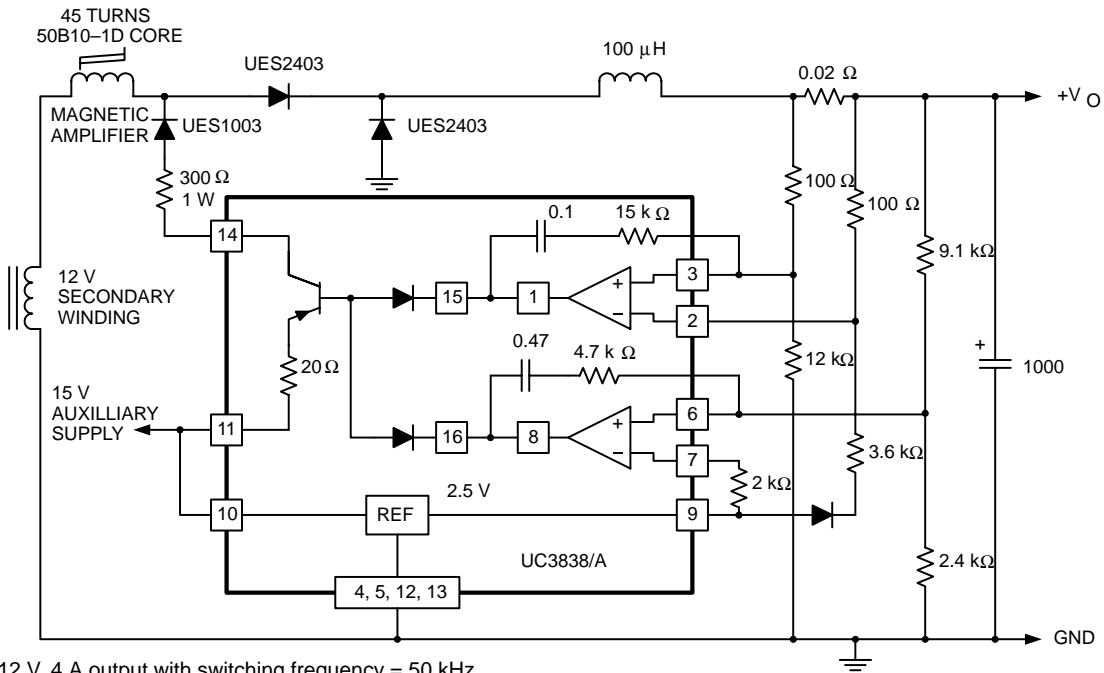
PARAMETER	TEST CONDITIONS	UC2838/UC2838A			UC3838/UC3838A			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
Offset voltage	$V_{CM} = 2.5\text{ V}$			5			10	mV
Input bias current	$V_{IN} = 0\text{ V}$			-1			-1	μA
Input offset voltage				100			100	nA
Minimum output swing		0.4		18	0.4		18	V
Output sink current	$V_O = 5\text{ V}$	1	10	30	1	10	30	mA
Output source current	$V_O = 0\text{ V}$	-1	-10	-20	-1	-10	-20	mA
A_{VOL} (open loop gain)	$V_O = 1\text{ V}$ to 11 V	100	120		100	120		dB
C_{MRR} (common mode rejection ratio)	$V_{IN} = 1\text{ V}$ to 11 V	70	80		70	80		dB
PSRR (power supply rejection ratio)	$V_{CC} = 10\text{ V}$ to 20 V	70	100		70	100		dB
Gain bandwidth	See Note 1	0.6	0.8		0.6	0.8		MHz

NOTE: 1. These parameters are ensured by design but not 100% tested in production.

reset drive

PARAMETER	TEST CONDITIONS	UC2838/UC2838A			UC3838/UC3838A			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	
Input leakage	$V_{DR} = 40\text{ V}$			10			10	μA
Output leakage	$V_R = -120\text{ V}$			-100			-100	μA
Input current	$I_R = -50\text{ mA}$		-1	-2		-1	-2	mA
Maximum reset current	$I_{DR} = -3\text{ mA}$	-100	-120	-200	-100	-120	-200	mA
Transconductance	$I_R = -10\text{ mA}$ to -50 mA	0.03	0.042	0.055	0.03	0.042	0.055	A/V

typical application



NOTE: 12 V, 4 A output with switching frequency = 50 kHz.

APPLICATION INFORMATION

**GAIN MAGNITUDE/PHASE
 VS
 SIGNAL FREQUENCY**

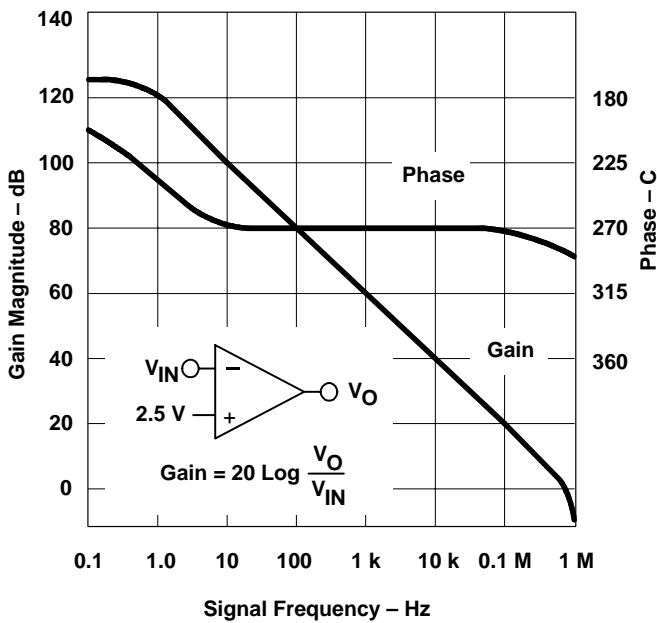


Figure 1.

**GAIN MAGNITUDE
 VS
 SIGNAL FREQUENCY**

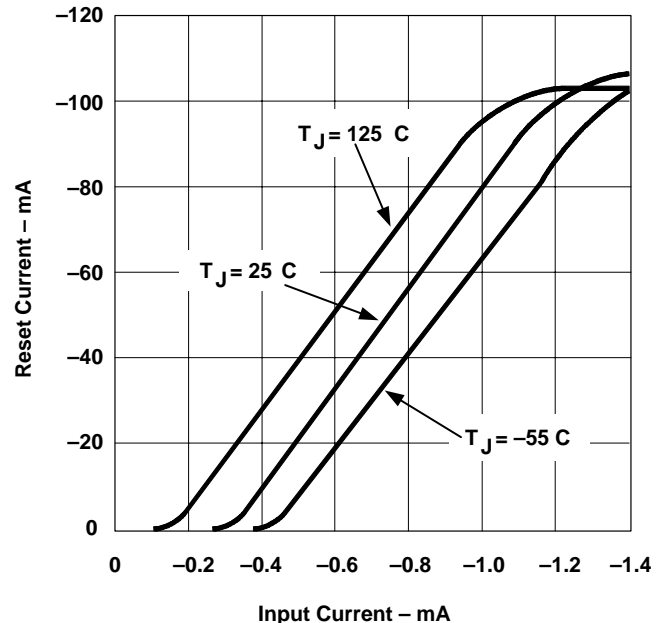


Figure 2.

APPLICATION INFORMATION

RESET CURRENT
vs
RESET VOLTAGE

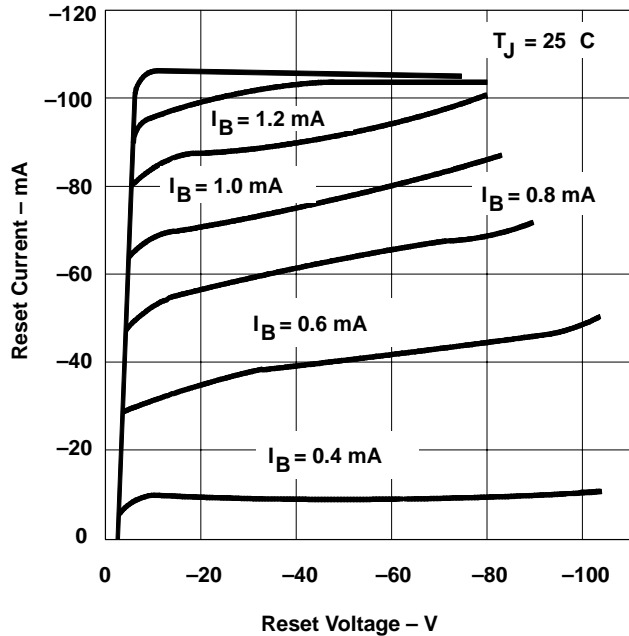


Figure 3.

GAIN MAGNITUDE/PHASE
vs
SIGNAL FREQUENCY

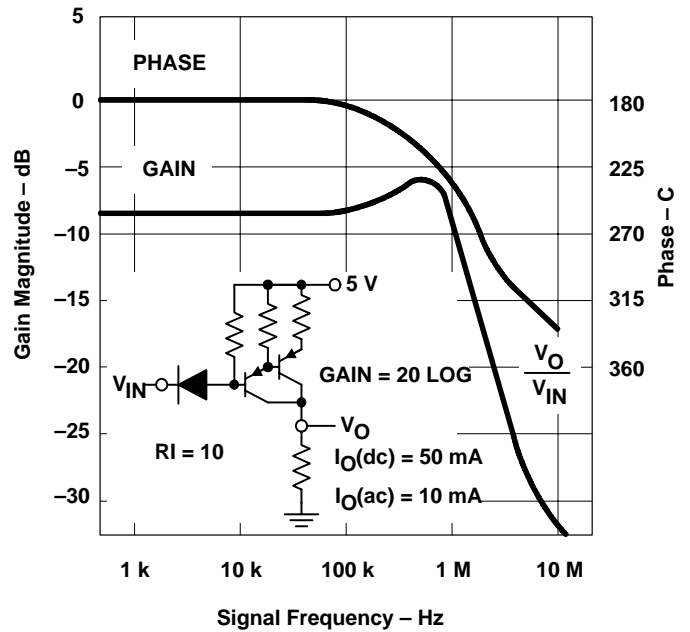


Figure 4.

RESET CURRENT
vs
INPUT CURRENT

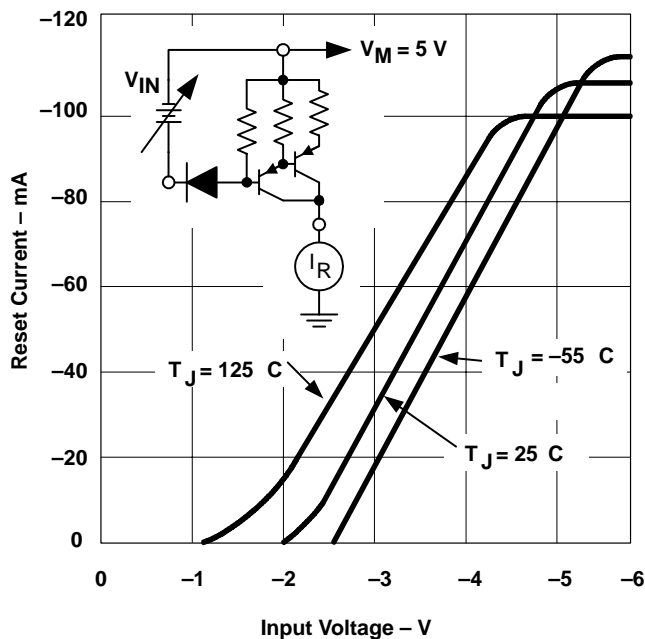


Figure 5.

REFERENCE VOLTAGE OUTPUT
vs
JUNCTION TEMPERATURE

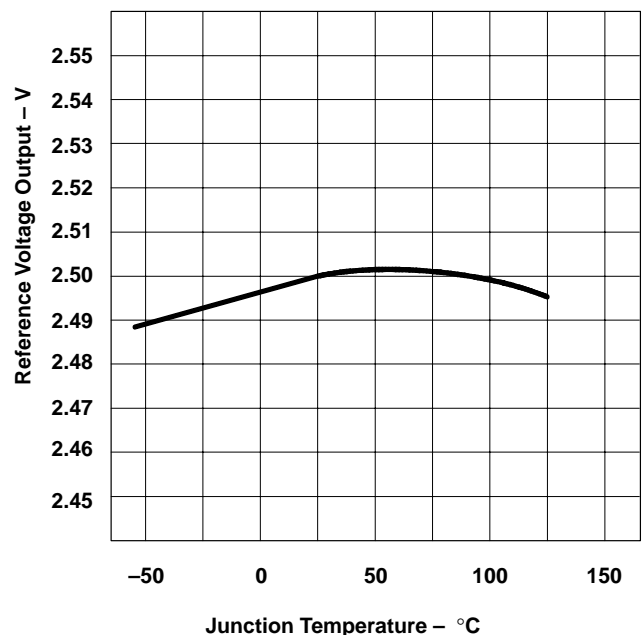


Figure 6.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
UC2838AJ	NRND	CDIP	J	16		TBD	Call TI	Call TI	-40 to 85		
UC2838AN	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	-40 to 85	UC2838AN	
UC2838ANG4	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	-40 to 85		
UC2838AQ	NRND	PLCC	FN	20		TBD	Call TI	Call TI	-40 to 85		
UC2838AQTR	OBSOLETE	PLCC	FN	20		TBD	Call TI	Call TI	-40 to 85		
UC3838ADW	OBSOLETE	SOIC	DW	16		TBD	Call TI	Call TI	0 to 70		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF UC3838A :

- Military: [UC1838A](#)

NOTE: Qualified Version Definitions:

- Military - QML certified for Military and Defense Applications

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

IMPORTANT NOTICE FOR TI DESIGN INFORMATION AND RESOURCES

Texas Instruments Incorporated ("TI") technical, application or other design advice, services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using any particular TI Resource in any way, you (individually or, if you are acting on behalf of a company, your company) agree to use it solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources.

You understand and agree that you remain responsible for using your independent analysis, evaluation and judgment in designing your applications and that you have full and exclusive responsibility to assure the safety of your applications and compliance of your applications (and of all TI products used in or for your applications) with all applicable regulations, laws and other applicable requirements. You represent that, with respect to your applications, you have all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. You agree that prior to using or distributing any applications that include TI products, you will thoroughly test such applications and the functionality of such TI products as used in such applications. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

You are authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING TI RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY YOU AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

You agree to fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of your non-compliance with the terms and provisions of this Notice.

This Notice applies to TI Resources. Additional terms apply to the use and purchase of certain types of materials, TI products and services. These include; without limitation, TI's standard terms for semiconductor products (<http://www.ti.com/sc/docs/stdterms.htm>), [evaluation modules](#), and [samples](http://www.ti.com/sc/docs/sampterm.htm) (<http://www.ti.com/sc/docs/sampterm.htm>).

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2017, Texas Instruments Incorporated